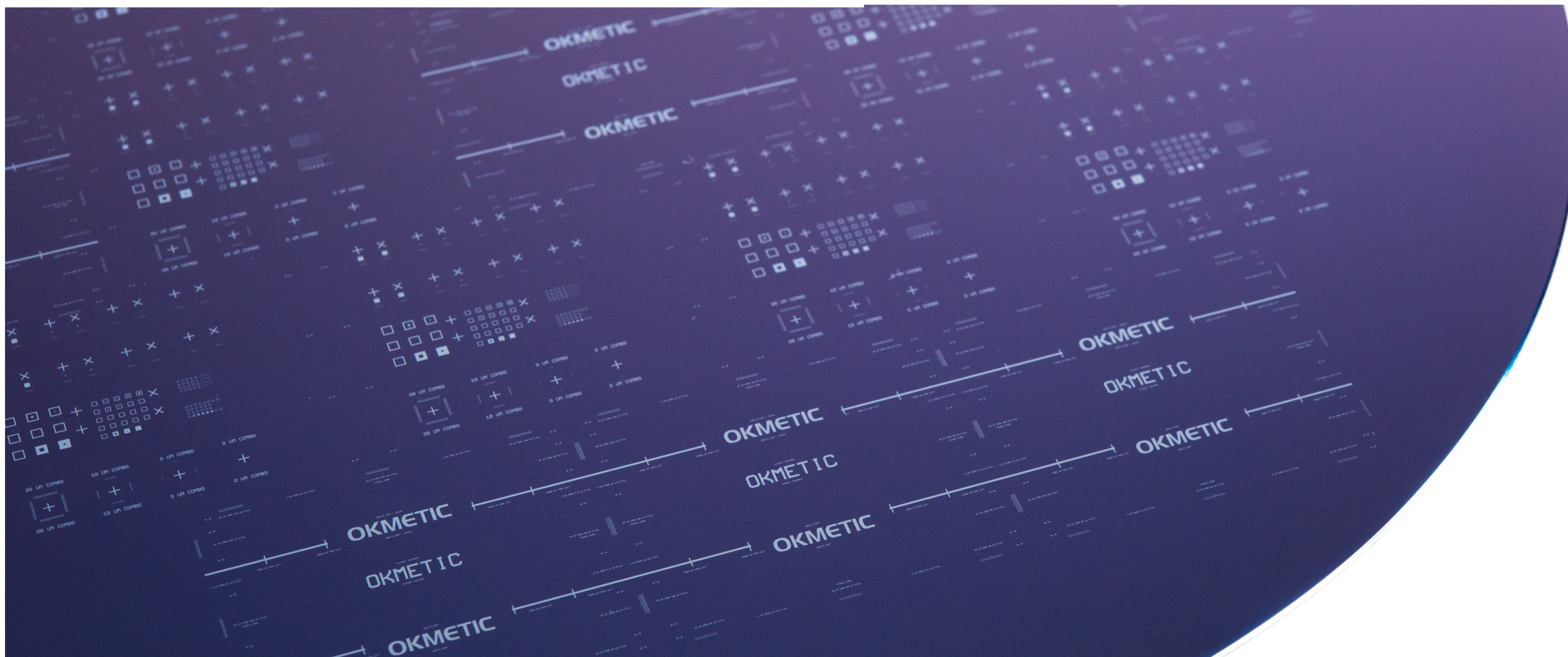


OKMETIC



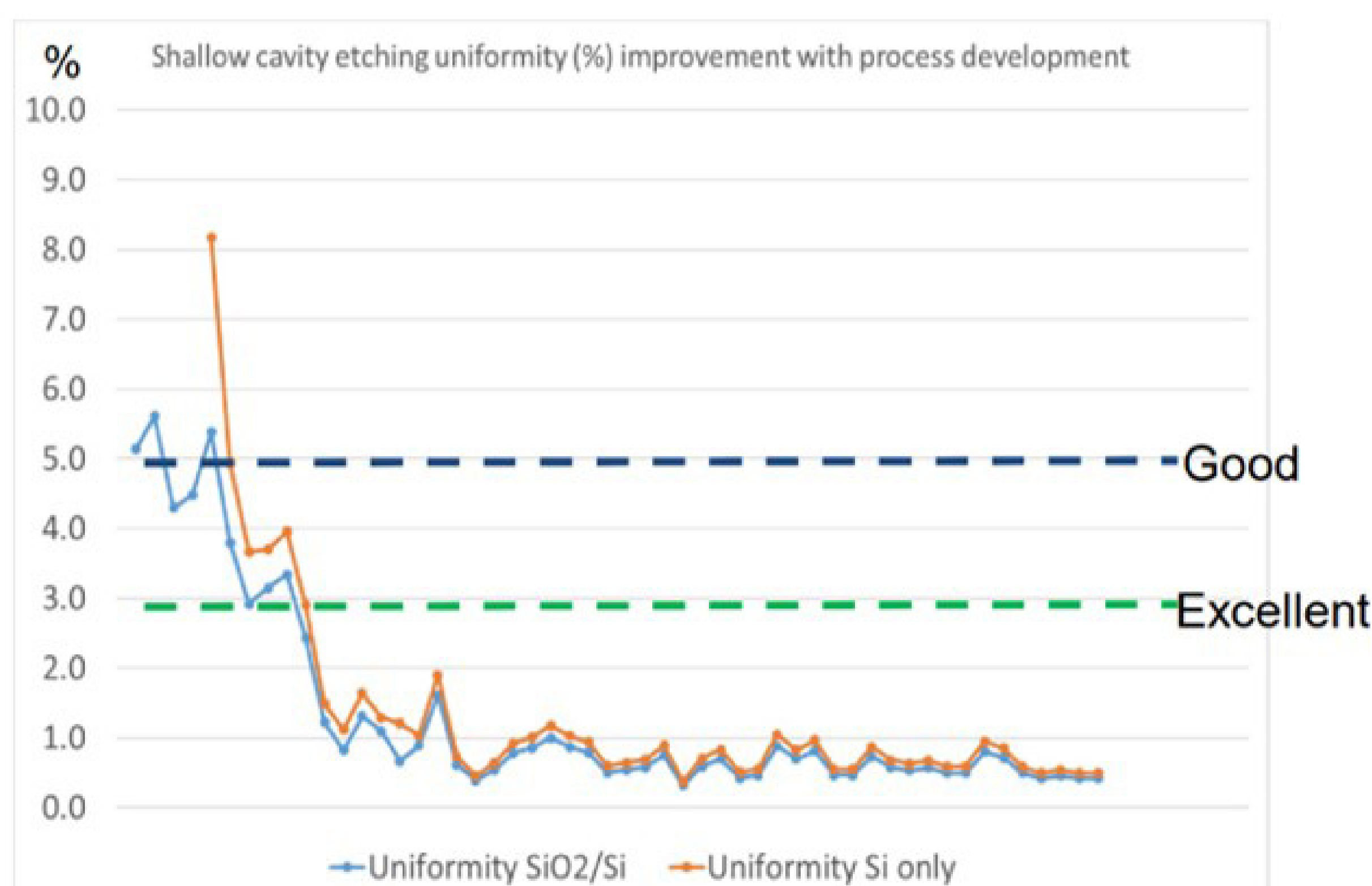
OKMETIC SILICON WAFERS WITH BUILT-IN PATTERNS OPTIMIZE MEMS PROCESS

Wafers with built-in patterns and buried cavities

- SSP, DSP and SOI including cavity SOI (C-SOI®)
- Fully in-house process covering crystal growth, wafering, lithography, DRIE and fusion bonded SOI
- Customer device design and process is the starting point for customized wafer solution.
- Superior wafer quality and reliability compared to POR.
- Fully CMOS compatible processes.

Benefits for MEMS manufacturers:

- Sensors with improved performance, reliability, and higher level of integration
- More design flexibility, reduced footprint, simplified process
- Allocation of equipment and engineering resources on value adding process steps for the end application
- Increased selection of sensor designs without extra investments
- Lower Total Cost of Ownership and shorter time to market



SUPERIOR UNIFORMITY
WHEN ETCHING SHALLOW
CAVITIES AND DEEP OR
COMPLICATED STRUCTURES

Picture: <1% etching variability for cavities <2µm depth